



#### N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BVDSS	RDS(ON)	I <sub>D</sub> T <sub>A</sub> = +25°C
20V	0.45Ω @ V <sub>GS</sub> = 4.5V	0.87A
200	0.6Ω @ V <sub>GS</sub> = 2.5V	0.76A

## **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN2710UTQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

## **Description and Applications**

This new generation MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Load Switch
- Power Management Functions

### **Mechanical Data**

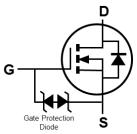
- Case: SOT523
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Alloy 42 Leadframe. Solderable per MIL-STD-202, Method 208 63
- Terminal Connections: See Diagram
- Weight: 0.002 grams (Approximate)



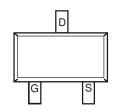


SOT523

Top View







Top View

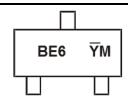
### Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2710UTQ-7	SOT523	3000/Tape & Reel
DMN2710UTQ-13	SOT523	10000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## **Marking Information**



BE6 = Product Type Marking Code YM = Date Code Marking  $\overline{\gamma}$  = Year (ex: H = 2020) M = Month (ex: 9 = September)

### Date Code Key

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	Н	ı	J	K	L	М	N	0	Р	R	S	T
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



## **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Char	acteristic		Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	20	V
Gate-Source Voltage			V <sub>GSS</sub>	±6	V
Continuous Drain Current Steady $T_A = +25^{\circ}C$ Note 6) $V_{GS} = 4.5V$ State $T_A = +75^{\circ}C$			lD	0.87 0.7	А
Maximum Continuous Body Diode Forward Current (Note 6)			Is	0.65	Α
Pulsed Drain Current (10µs F	Pulse, Duty Cy	cle = 1%)	IDM	5.6	A

# Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.32	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	395	°C/W
Total Power Dissipation (Note 6)		PD	0.52	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{ heta JA}$	241	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

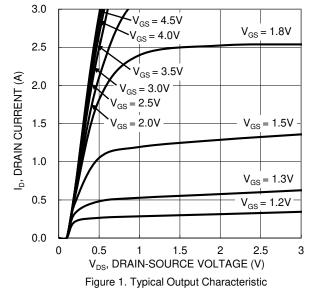
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BVDSS	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	100	nA	$V_{DS} = 20V$ , $V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±1.0	μΑ	$V_{GS} = \pm 4.5V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)	·					
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.5	_	1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
		_	0.14	0.45		V <sub>G</sub> S = 4.5V, I <sub>D</sub> = 600mA
Static Drain-Source On-Resistance	RDS(ON)	_	0.17	0.6	Ω	$V_{GS} = 2.5V, I_D = 500mA$
		_	0.22	0.75		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 350mA
Diode Forward Voltage	V <sub>SD</sub>	_	0.7	1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 150mA
DYNAMIC CHARACTERISTICS (Note 8)			•	•		•
Input Capacitance	Ciss	_	42	_	pF	
Output Capacitance	Coss	_	13	_	pF	$V_{DS} = 16V, V_{GS} = 0V$ - f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	6.5	_	pF	1 = 1.0WH 12
Gate Resistance	Rg	_	1.6	_	kΩ	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge	Qg	_	0.6	_	nC	V 45V V 40V
Gate-Source Charge	Qgs		0.1	_	nC	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 10V,
Gate-Drain Charge	$Q_{gd}$		0.1	_	nC	$I_D = 250 \text{mA}$
Turn-On Delay Time	td(ON)		4.9	_	ns	
Turn-On Rise Time	tr		3.1	_	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$
Turn-Off Delay Time	t <sub>D(OFF)</sub>		386	_	ns	$R_L = 47\Omega$ , $R_g = 10\Omega$
Turn-Off Fall Time	tr		174	_	ns	I <sub>D</sub> = 200mA
Reverse Recovery Time	t <sub>RR</sub>	_	88	_	ns	$I_F = 1.0A$ , $di/dt = 100A/\mu s$
Reverse Recovery Charge	Q <sub>RR</sub>	_	29	_	nC	I <sub>F</sub> = 1.0A, di/dt = 100A/μs

Notes:

Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.

<sup>8.</sup> Guaranteed by design. Not subject to product testing.





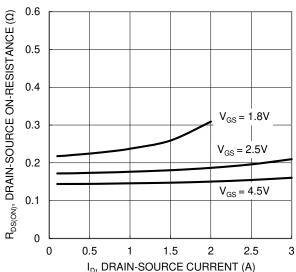


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

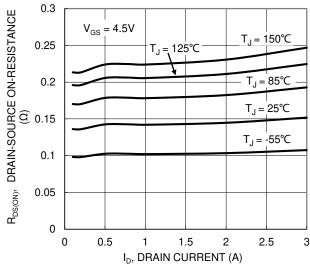


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

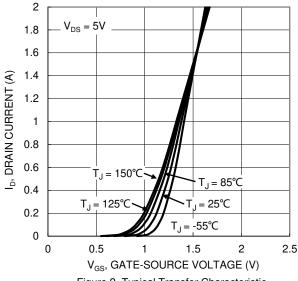


Figure 2. Typical Transfer Characteristic

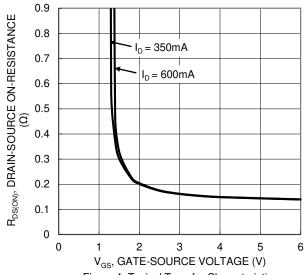


Figure 4. Typical Transfer Characteristic

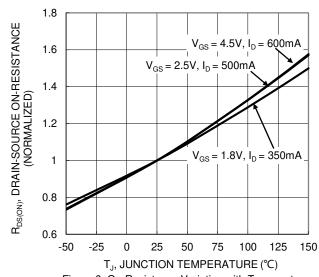


Figure 6. On-Resistance Variation with Temperature



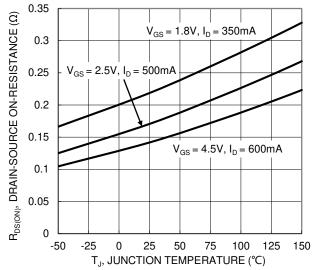


Figure 7. On-Resistance Variation with Temperature

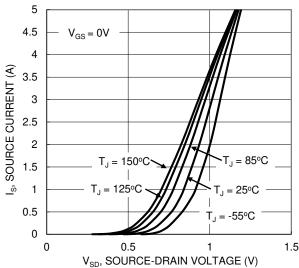


Figure 9. Diode Forward Voltage vs. Current

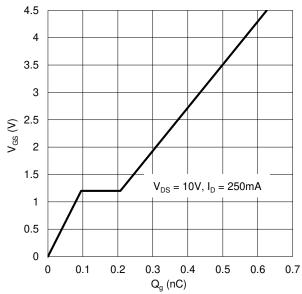


Figure 11. Gate Charge

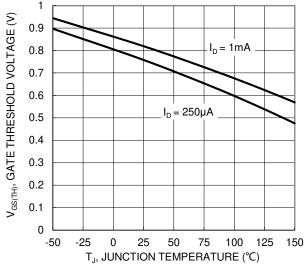
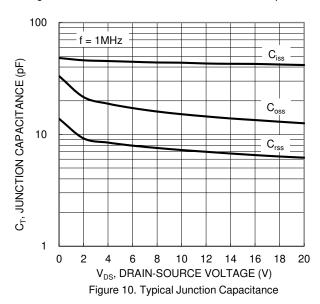


Figure 8. Gate Threshold Variation vs. Junction Temperature



10  $P_W = 100 \mu s$ ID, DRAIN CURRENT (A) = 1ms  $P_W = 10ms$ 0.1  $P_{W} = 100m$  $T_{J(Max)} = 150$ °C = 10s0.01 T<sub>C</sub> = 25°C DC Single Pulse DUT on 1\*MRP  $V_{GS} = 4.5V$ 0.001 0.1 100 10 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



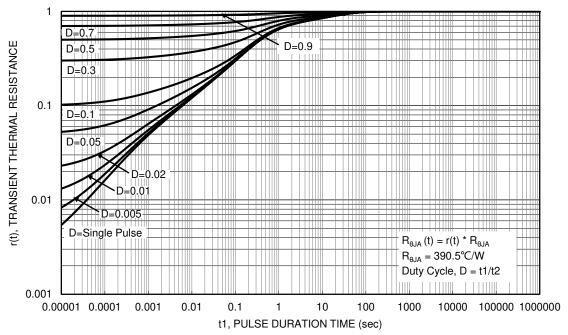


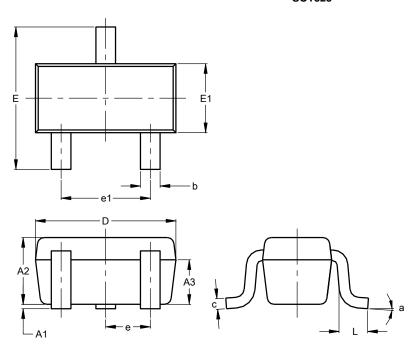
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT523**

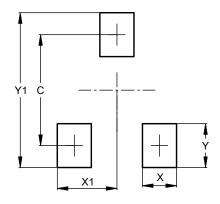


SOT523						
Dim	Min	Max	Тур			
<b>A</b> 1	0.00	0.10	0.05			
A2	0.60	0.80	0.75			
<b>A3</b>	0.45	0.65	0.50			
b	0.15	0.30	0.22			
С	0.10	0.20	0.12			
D	1.50	1.70	1.60			
Е	1.45	1.75	1.60			
E1	0.75	0.85	0.80			
е	0.50 BSC					
e1	0.90	1.10	1.00			
L	0.20	0.40	0.33			
а	0°		8°			
All Dimensions in mm						

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT523**



Dimensions	Value (in mm)			
С	1.29			
Х	0.40			
X1	0.70			
Υ	0.51			
V1	1.80			



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